

MOSFET

239A, 100V, 3mΩ, N-CHANNEL MOSFET

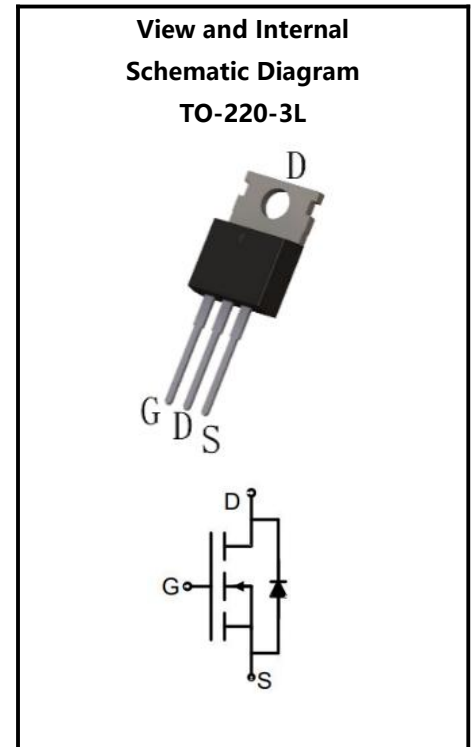
Features

- ◆ Low gate charge
- ◆ Low Ciss
- ◆ Fast switching

Applications

- ◆ Networking
- ◆ Secondary Side SR
- ◆ High-frequency SMPS
- ◆ DC-DC Power Management

Parameter	Values	Unit
BV_{DSS}	100	V
I_D	239	A
$R_{Dson(max)}$	3	mΩ
$V_{GS(th)}(Typ)$	3	V



Ordering Code	Marking	Package	Packaging
X3N10GHB3B	X3N10GHB3B	TO-220-3L	Tape and Reel

Absolute Maximum Ratings($T_C=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Drain-Source Voltage	V_{DSS}	-	-	100	V	-
Gate-Source Voltage	V_{GS}	-20	-	20	V	-
Continuous Drain Current(Note 1)	I_D	-	-	239	A	$T_C=25^{\circ}C$
		-	-	151	A	$T_C=100^{\circ}C$
Pulsed Drain Current(Note 2)	I_{DM}	-	-	956	A	-
Single Pulse Avalanche Energy	E_{AS}	-	-	1008	mJ	$L=0.5mH, V_D=50V, T_C=25^{\circ}C$
Maximum Power Dissipation	P_D	-	-	320	W	$T_C=25^{\circ}C$
		-	-	2.6	W	$T_A=25^{\circ}C$
Operating Junction and Storage Temperature Range	T_{j}, T_{STG}	-50	-	150	$^{\circ}C$	-

Thermal Characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Thermal resistance , Junction to Case	$R_{th(J-C)}$	-	0.39	-	$^{\circ}C/W$	-
Thermal resistance , Junction to Ambient	$R_{th(J-a)}$	-	48	-		-

**Electrical Characteristics ($T_j=25^{\circ}\text{C}$, unless otherwise noted)****Static characteristics**

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Drain-Source Breakdown Voltage	BV_{DSS}	100	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	1	μA	$V_{DS}=100V, V_{GS}=0V$
Gate-Body Leakage Current, Forward	I_{GSSF}	-	-	100	nA	$V_{GS}=20V, V_{DS}=0V$
Gate-Body Leakage Current, Reverse	I_{GSSR}	-	-	-100	nA	$V_{GS}=-20V, V_{DS}=0V$
Gate-Source Threshold Voltage	$V_{GS(th)}$	2	-	4	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Drain-Source On-State Resistance	$R_{DS(on)}$	-	2.6	3	m Ω	$V_{GS}=10V, I_D=50A$
		-	3.4	5	m Ω	$V_{GS}=6V, I_D=25A$
Gate Resistance	R_g	-	3.4	-	Ω	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$
Forward Transconductance	g_{fs}	-	66	-	S	$V_{DS}=5V, I_D=50A$

Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Input Capacitance	C_{iss}	-	6126	-	pF	$V_{DS}=50V, V_{GS}=0V, f=1.0\text{MHz}$
Output Capacitance	C_{oss}	-	1293	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	77	-	pF	
Turn-On Delay Time	$t_{d(on)}$	-	37	-	ns	$V_{DD}=50V, V_{GS}=10V, R_g=6\Omega, I_D=80A$
Turn-On Rise Time	t_r	-	146	-	ns	
Turn-Off Delay Time	$t_{d(off)}$	-	106	-	ns	
Turn-Off Fall Time	t_f	-	121	-	ns	

Gate charge characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Total Gate Charge	Q_g	-	86	-	nC	$V_{DS}=50V, I_D=80A, V_{GS}=10V$
Gate-Source Charge	Q_{gs}	-	26	-	nC	
Gate-Drain Charge	Q_{gd}	-	26	-	nC	

Reverse diode

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Continuous Diode Forward Current	I_S	-	-	239	A	-
Pulsed Diode Forward Current	I_{SM}	-	-	956	A	-
Diode Forward Voltage	V_{SD}	-	-	1.2	V	$I_S=50A, V_{GS}=0V$
Reverse Recovery Time	t_{rr}	-	78	-	ns	$V_{DS}=50V, V_{GS}=0V, I_S=80A$
Reverse Recovery Charge	Q_{rr}	-	98	-	nC	$di/dt=100A/\mu s$

Notes

1. Computed continuous current assumes the condition of T_{j_Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under $T_{j_Max} = 150^{\circ}\text{C}$.

RATING AND CHARACTERISTIC CURVES



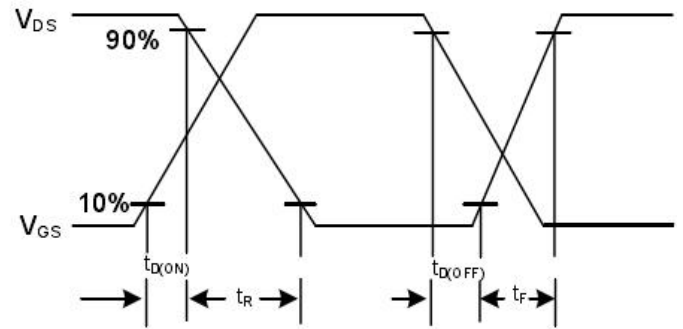
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms



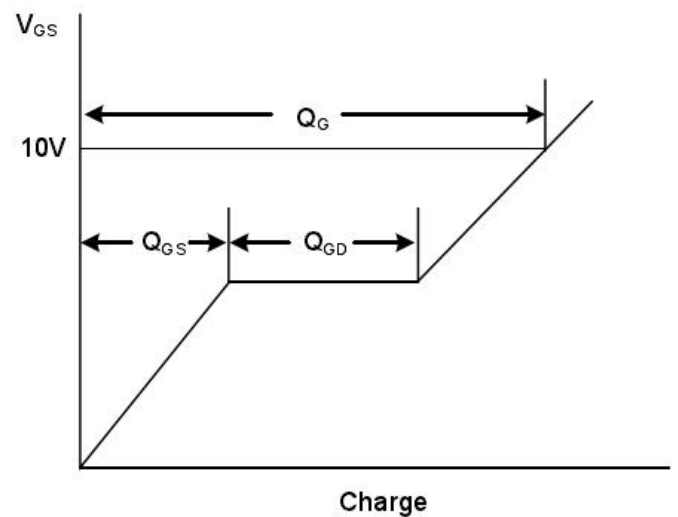
Switching Test Circuit



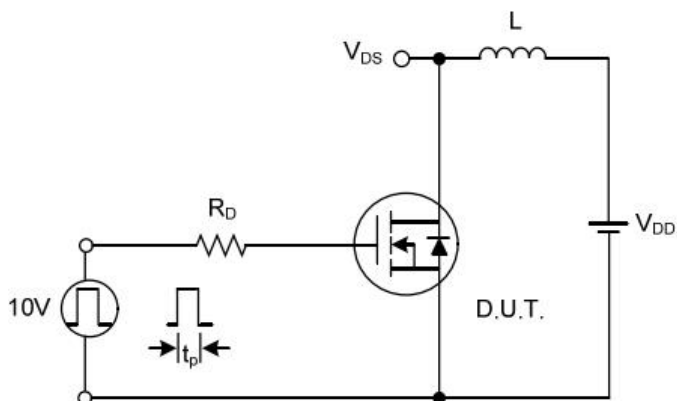
Switching Waveforms



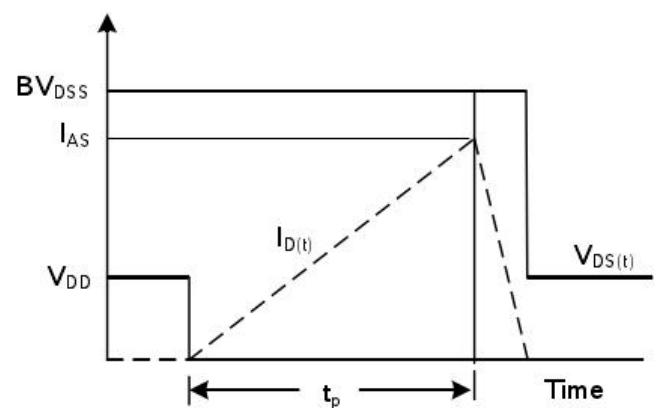
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

RATING AND CHARACTERISTIC CURVES

Figure.1 Output Characteristics $T_J=25^{\circ}\text{C}$

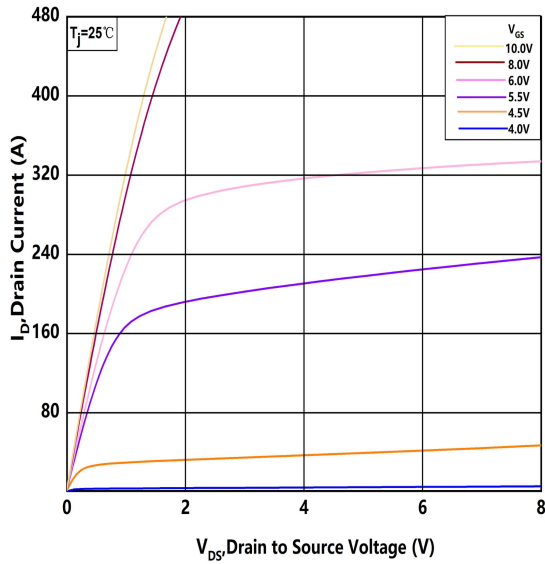


Figure.2 Transfer Characteristic for Various Junction Temperatures

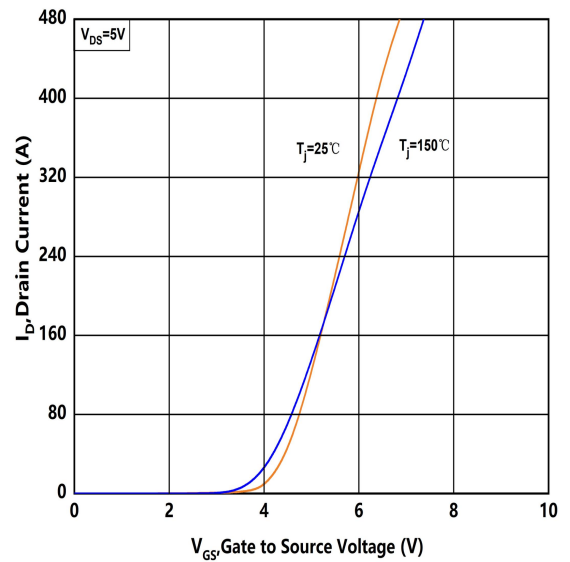


Figure.3 On-Resistance vs Drain Current For Various Gate Voltage

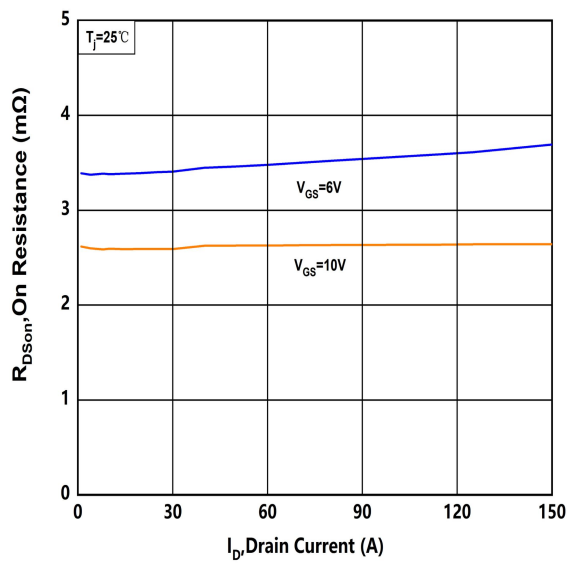


Figure.4 Typical On-Resistance vs Junction Temperature

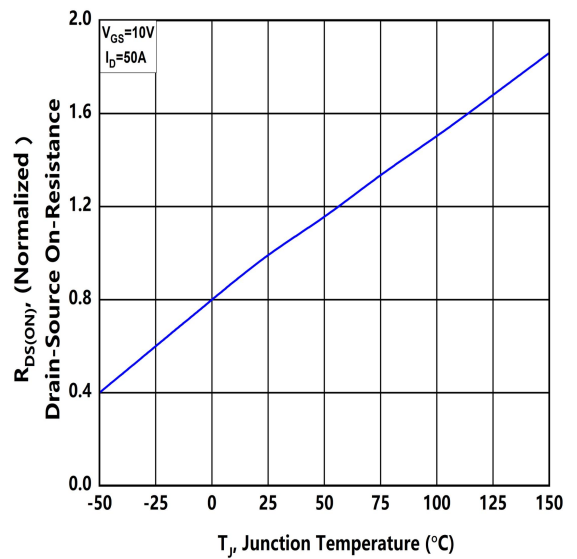


Figure.5 Typical Threshold Voltage vs Junction Temperature

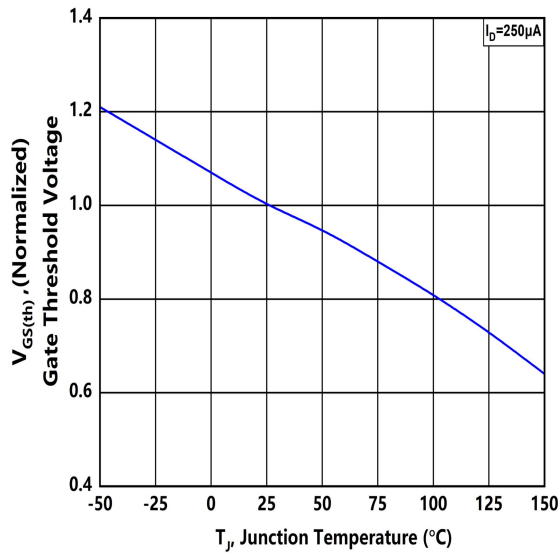


Figure.6 Typical Breakdown Voltage vs Junction Temperature

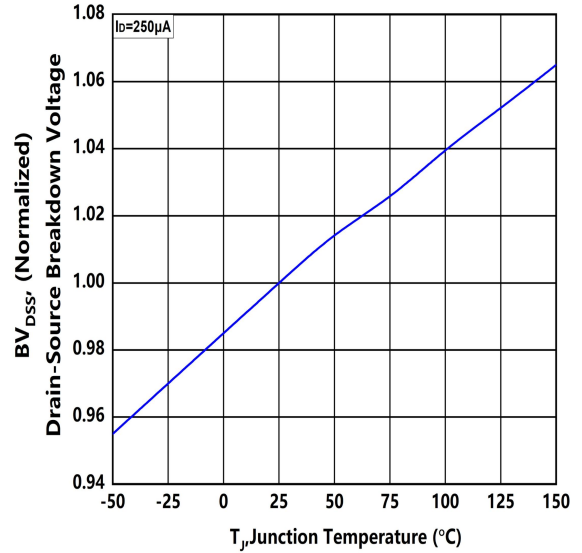


Figure.7 Typical Capacitance vs Drain to Source Voltage

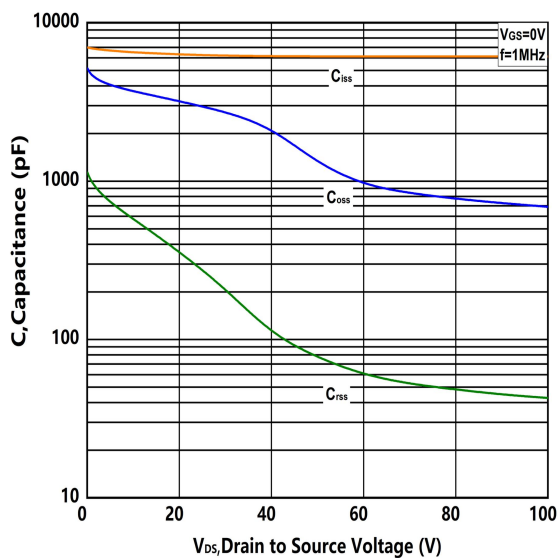


Figure.8 Typical Gate Charge vs Gate to Source Voltage

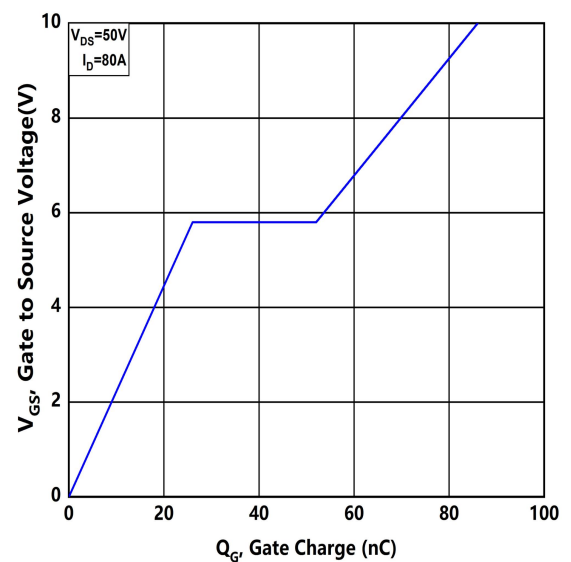


Figure.9 Typical Body Diode Characteristics

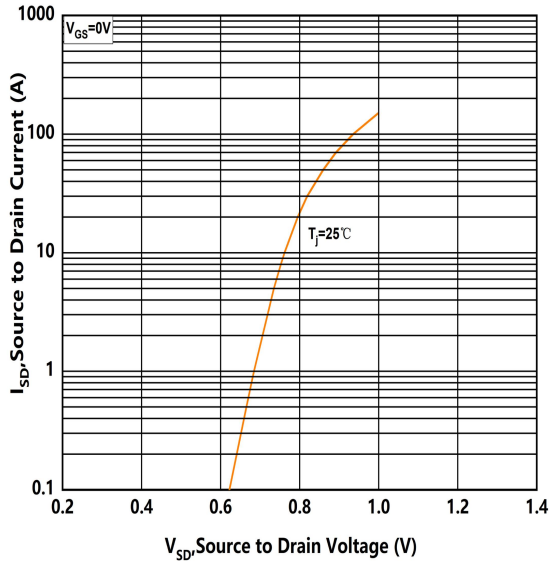


Figure.10 Maximum power Dissipation Derating vs Case Temperature

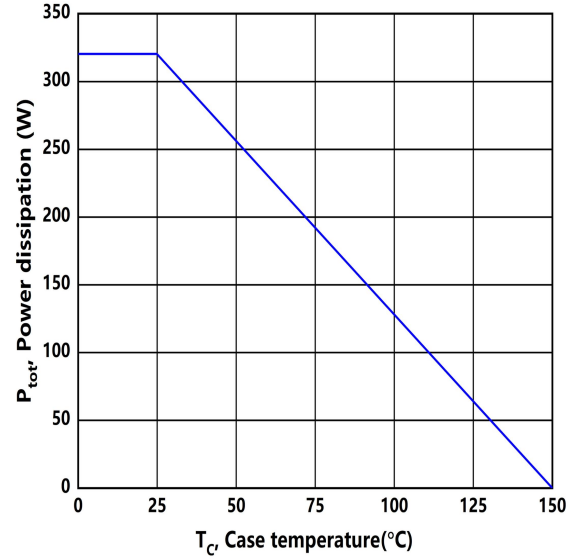


Figure.11 Continuous Drain Current Derating vs Case Temperature

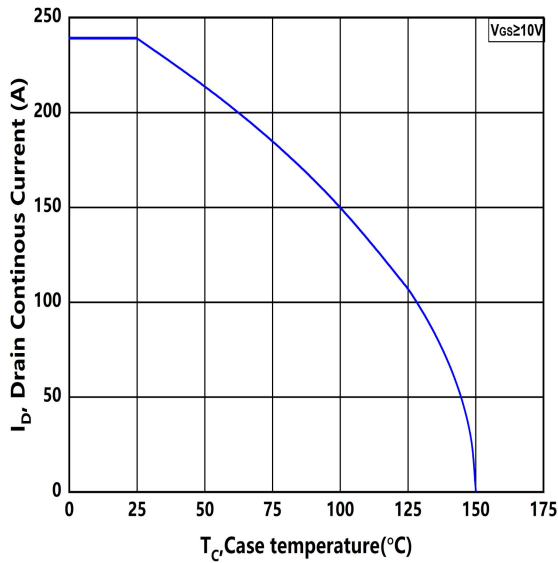


Figure.12 Safe Operating Area

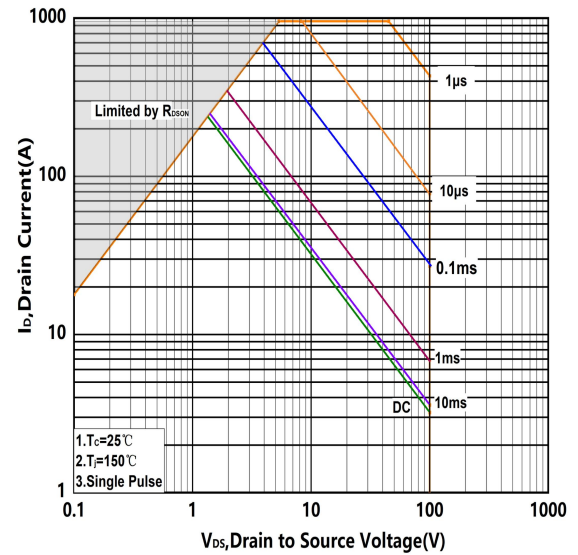
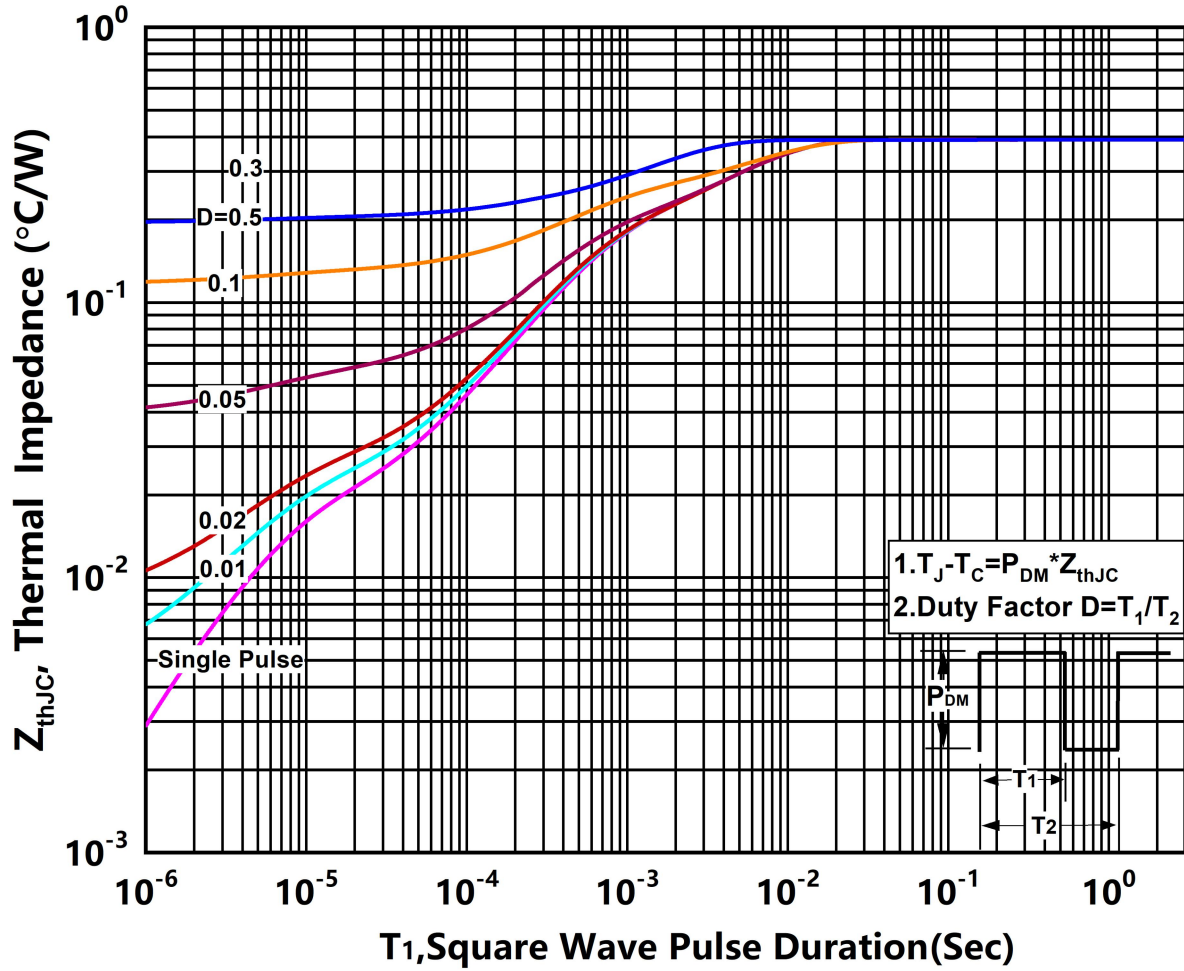
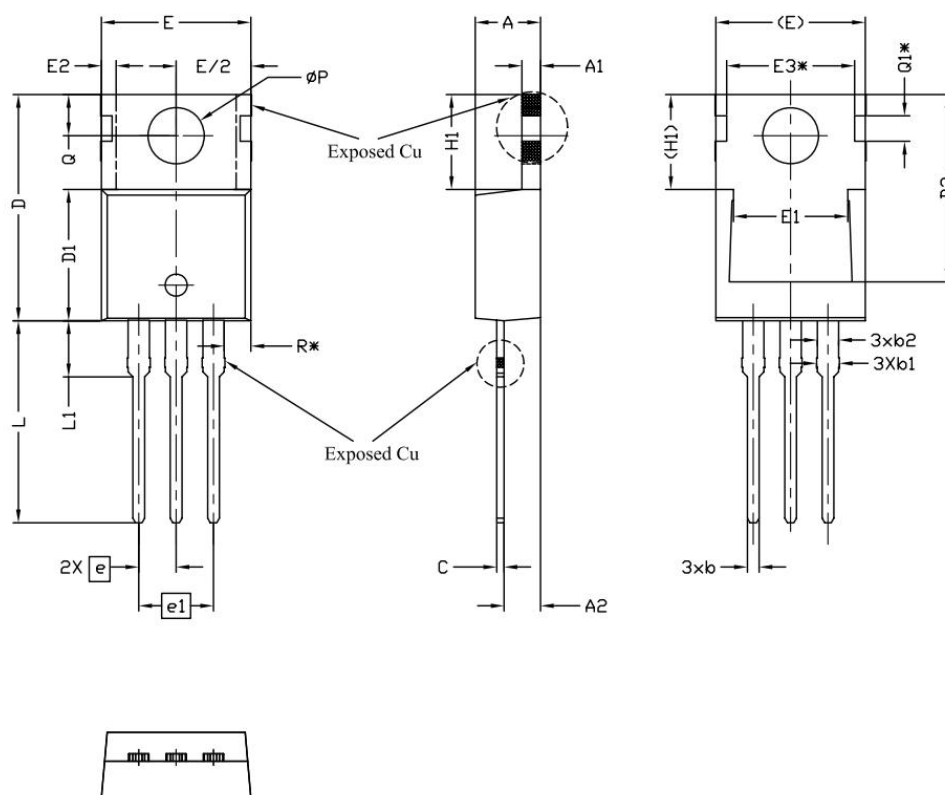


Figure.13 Transient Thermal Impedance (Junction - Case)



Package Outline:TO-220-3L



Note:

1. Package Reference: JEDEC TO220, Variation AB.
2. All Dimensions Are In mm.
3. Slot Required, Notch May Be Rounded
4. Dimension D & E Do Not Include Mold Flash. Mold Flash Shall Not Exceed 0.127mm Pre Side. These Dimensions Are Measured At The Outermost Extreme Of The Plastic Body.
5. Thermal Pad Contour Optional Within Dimensions E, H1, D2 & E1.
6. Dimension E2 & H1 Define A Zone Where Stamping And Singulation Irregularities Are Allowed.
7. "*" is reference .

SYMBOL	DIMENSIONS			NOTES
	MIN	NOM	MAX	
A	4.24	4.44	4.64	
A1	1.15	1.27	1.40	
A2	2.30	2.48	2.70	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
c	0.40	0.50	0.60	
D	14.70	15.37	16.00	4
D1	8.82	8.92	9.02	
D2	12.43	12.73	12.83	5
E	9.96	10.16	10.36	4,5
E1	6.86	7.77	8.89	5



E2	-	-	0.76	6
E3*	8.70REF.			
e	2.54BSC			
e1	5.08BSC			
H1	6.30	6.45	6.60	5,6
L	13.47	13.72	13.97	
L1	3.60	3.80	4.00	
ΦP	3.75	3.84	3.93	
Q	2.60	2.80	3.00	
Q1*	1.73REF.			
R*	1.82REF.			